



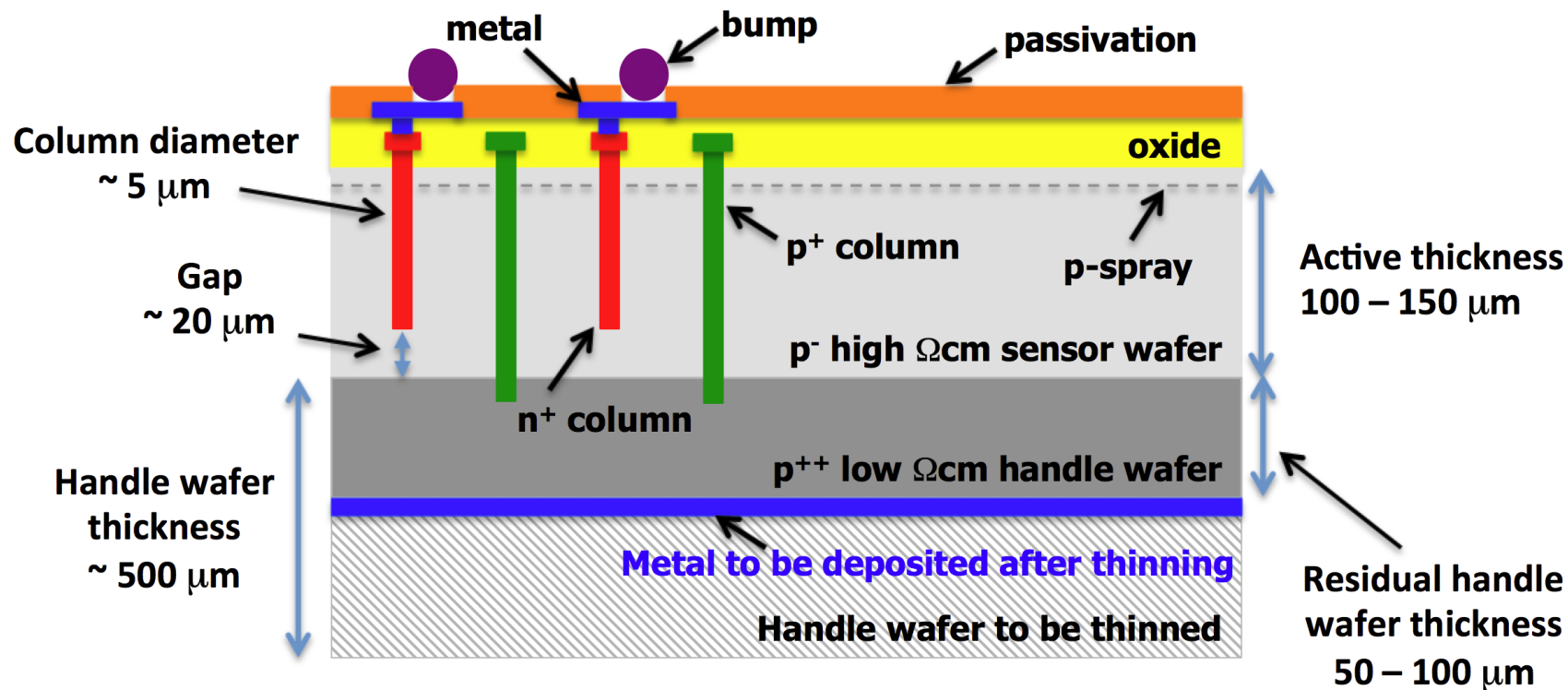
FE65-p2 / CHPIX65 3D sensor layout

Gian-Franco Dalla Betta

University of Trento and TIFPA INFN, Trento, Italy

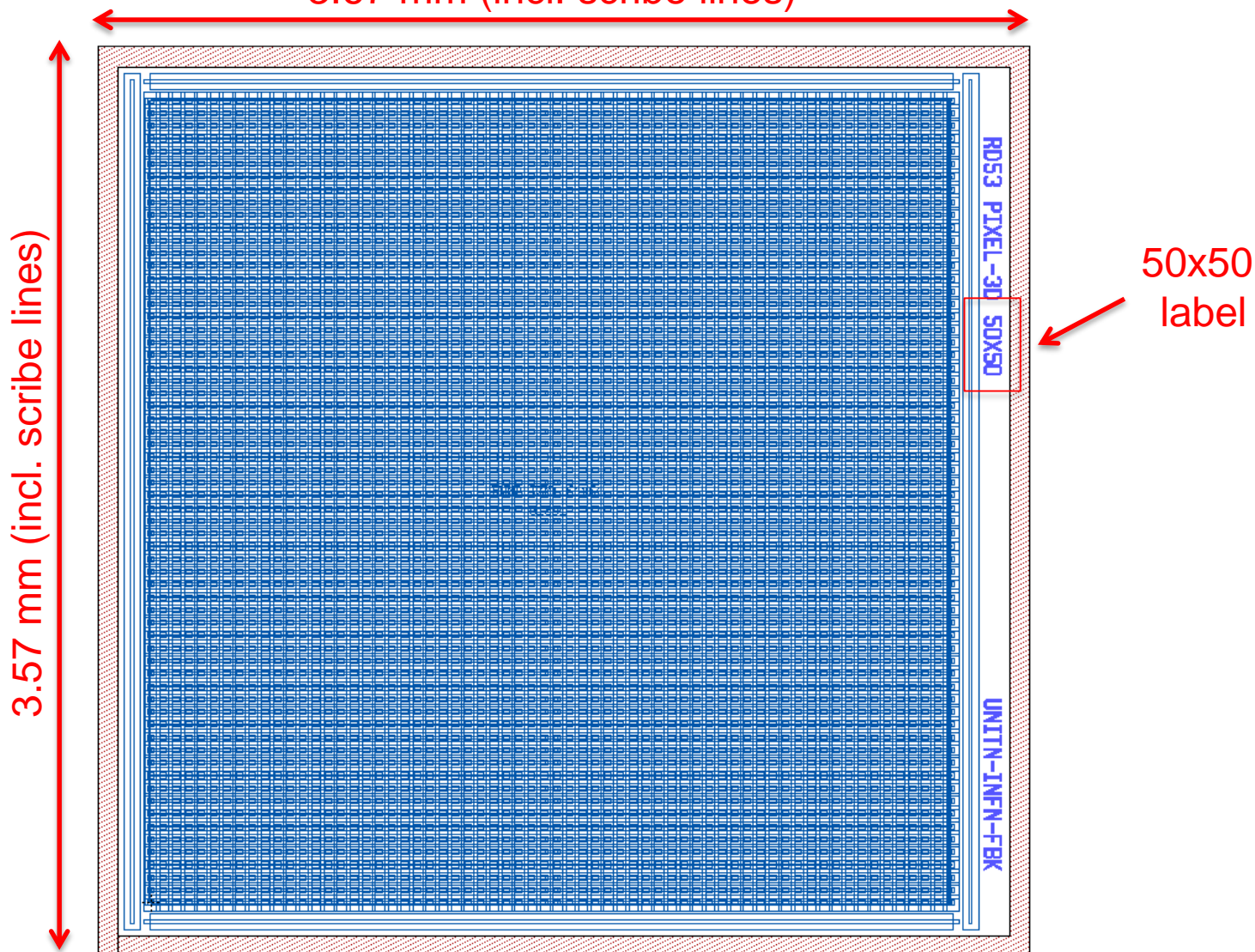
3D sensor cross section

- The sensors were fabricated at FBK on Silicon Silicon Direct Wafer Bonded substrates with a single-sided process. The active layer is 130 μm thick.
- On these prototypes the handle wafer was not thinned.

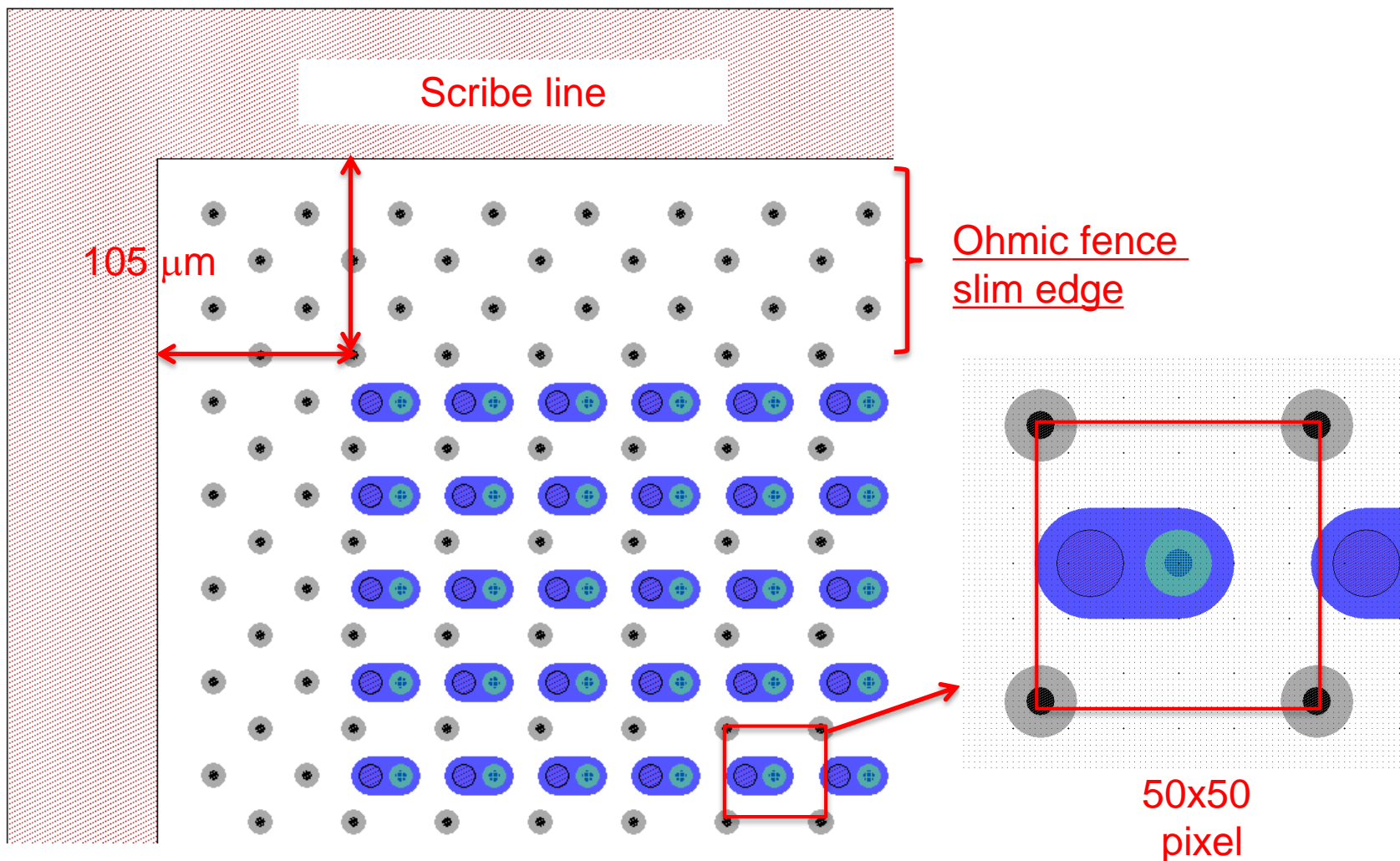


CHPIX65 3D sensors (1): 50x50

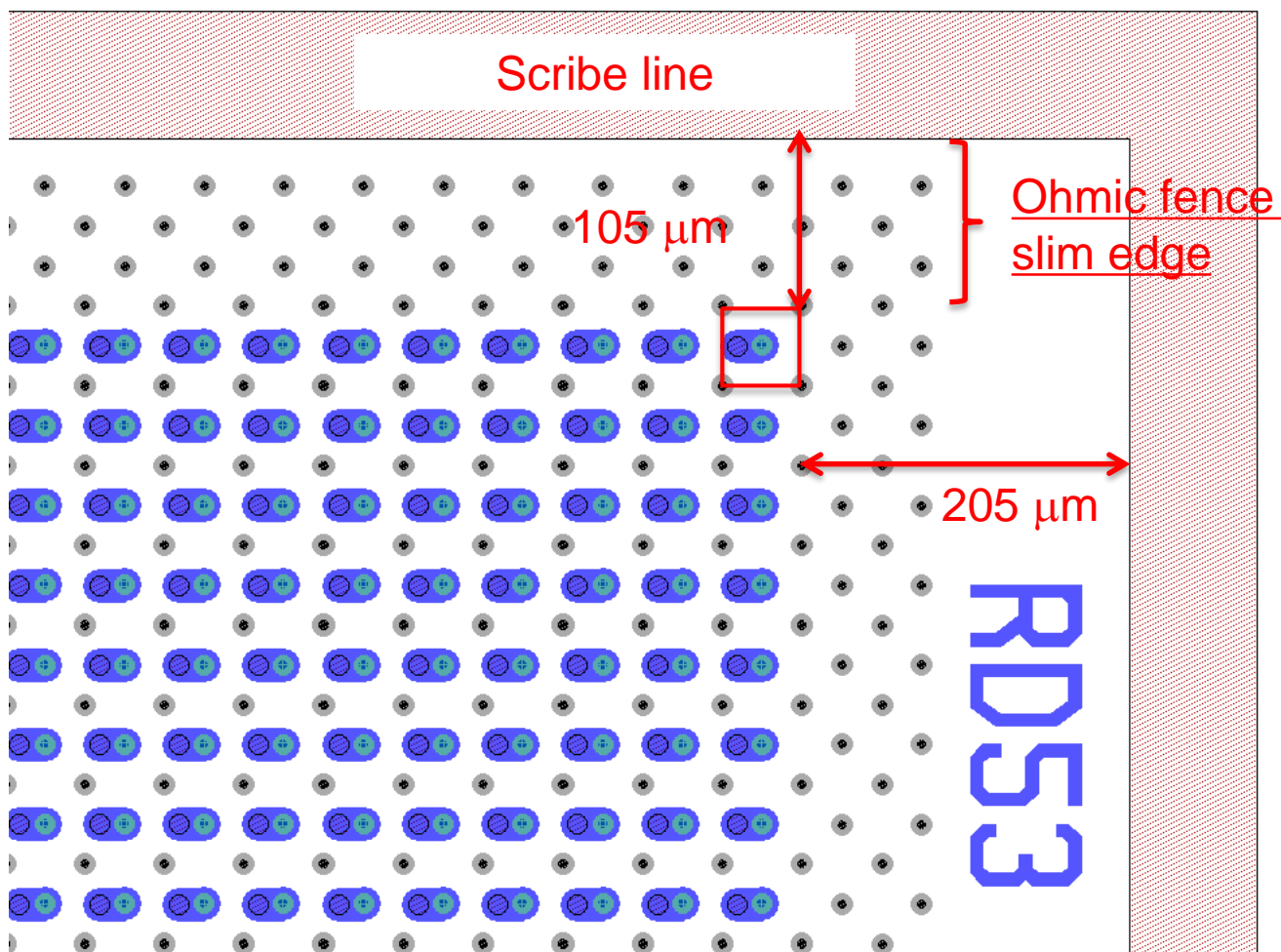
3.67 mm (incl. scribe lines)



CHPIX65 3D sensors (2): 50x50 Top left corner details

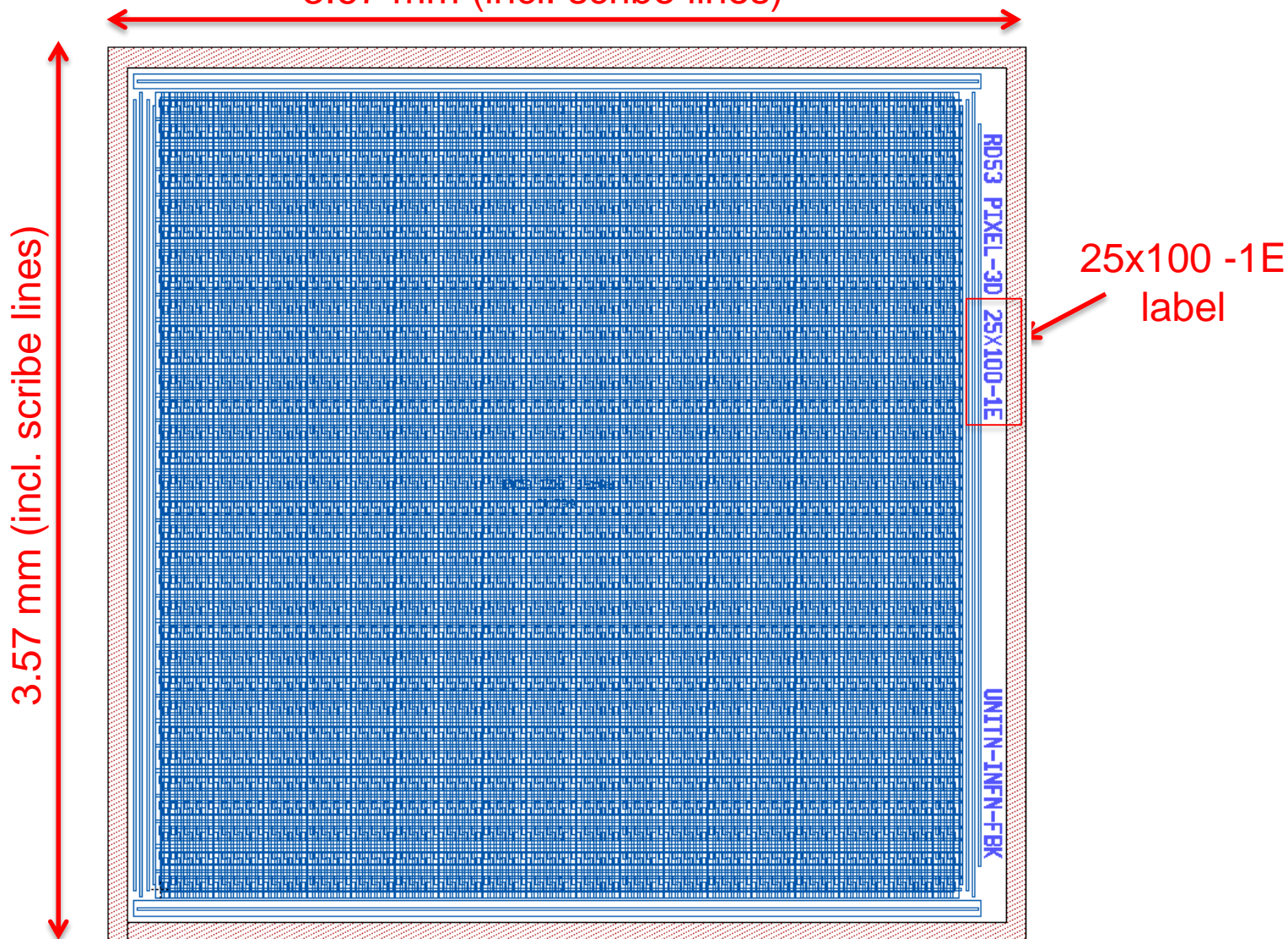


CHPIX65 3D sensors (3): 50x50 Top right corner details



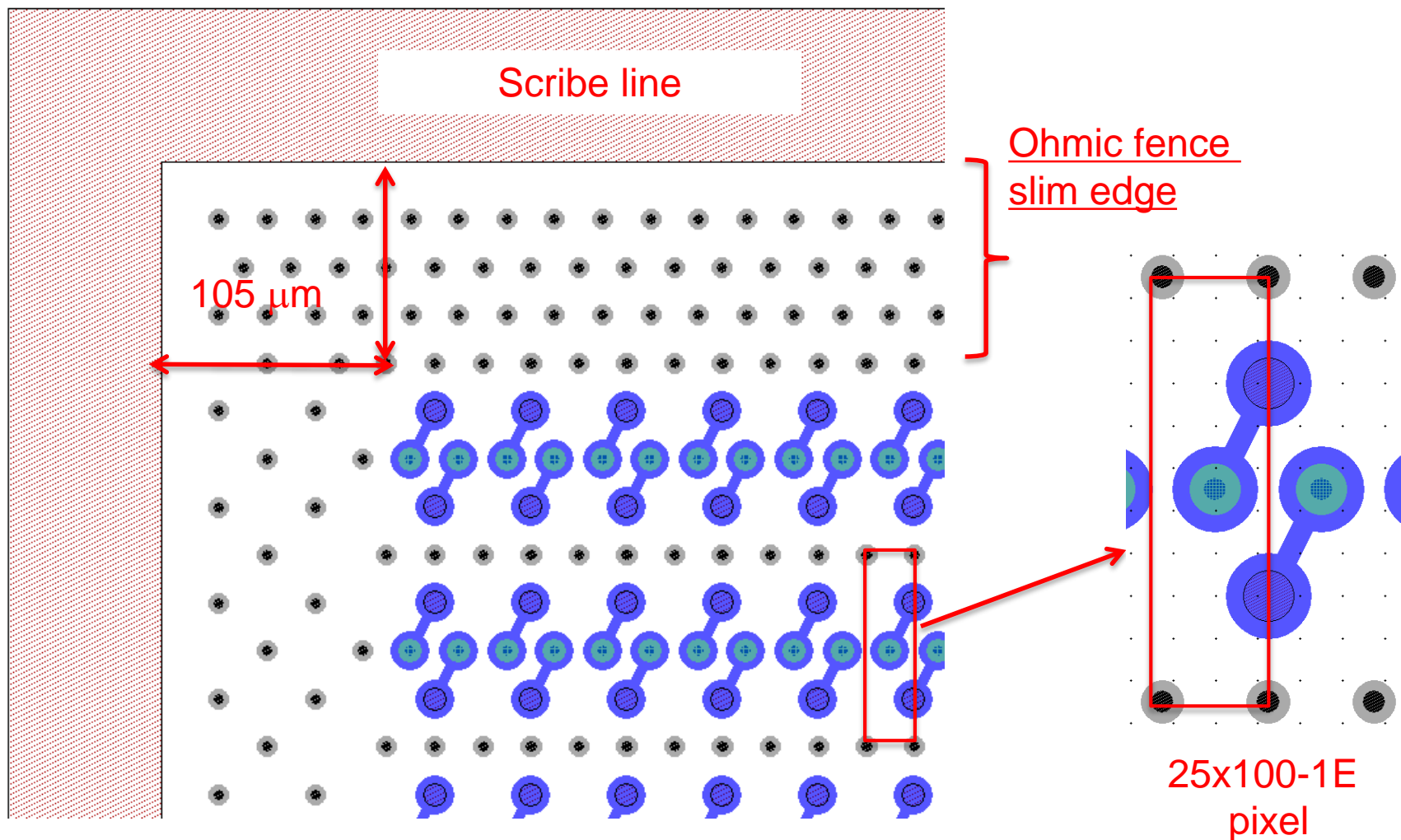
CHPIX65 3D sensors (4): 25x100-1E

3.67 mm (incl. scribe lines)



CHPIX65 3D sensors (5): 25x100-1E

Top left corner details



CHPIX65 3D sensors (6): 25x100-1E

Top right corner details

